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03-21-2001



Docket No.: 500.39826X00

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U.S. DEPARTMENT OF COMMERCE
Patent and Trademark Office

101643162

To the Honorable Commissioner of Patents and Trademarks. Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):
Seiichiro KANNO, Ryoji NISHIO, Tsutomu TETSUKA,
Junichi TANAKA, Hideyuki YAMAMOTO, Kazuyuki
IKENAGA, Saburou KANAI

Additional name(s) of conveying party(ies) attached? Yes No

2. Name and address of receiving party(ies):
Name: Hitachi, Ltd.
Street Address: 6, Kanda Surugadai 4-chome, Chiyoda-ku
City: Tokyo
Country: Japan

Additional name(s) & address(es) attached? Yes No

31000 U.S. P.O.
09/799527
03/07/01

3. Nature of conveyance:
 Assignment Merger
 Security Agreement Change of Name
 Other _____
Execution Date: Feb. 19,20,16, 2001

4. Application number(s) or patent number(s):
If this document is being filed together with a new application, the execution date of the application is: Feb. 19,20,16, 2001

A. Patent Application No.(s)
09/799527

Additional numbers attached? Yes No

B. Patent No.(s)

5. Name and address of party to whom correspondence concerning document should be mailed:
Name: ANTONELLI, TERRY, STOUT & KRAUS, LLP
Internal Address:
Street Address: 1300 North Seventeenth Street
Suite 1800
City: Arlington State: VA Zip: 22209

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41).....\$40.00
 Enclosed
 Any deficiencies may be charged to deposit account
 Authorized to be charged to deposit account

8. Deposit account number: 01-2135
(Attach duplicate copy of this page if paying by deposit account)

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9. Statement and signature.
To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Melvin Kraus _____
Name of Person Signing
Attorney Registration No. 22,466
Total number of pages including cover sheet, attachments, and document: 2

Melvin Kraus _____
Signature

March 7, 2001
Date

OMB No. 0651-0011 (exp. 4/94)

03/12/2001 TBESHAH1 00000061 09799527

04 FC:581

40.00 OP

PATENT
REEL: 011593 FRAME: 0071

ASSIGNMENT

(讓渡証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by HITACHI, LTD., a corporation organized under the laws of Japan, located at 6, Kanda Surugadai 4-chome, Chiyoda-ku, Tokyo, Japan, receipt of which is hereby acknowledged I do hereby sell and assign to said HITACHI, LTD., its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

SEMICONDUCTOR MANUFACTURING APPARATUS AND METHOD OF PROCESSING SEMICONDUCTOR WAFER USING PLASMA, AND WAFER VOLTAGE PROBE

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said HITACHI, LTD., its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted, as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said HITACHI, LTD.

Signed on the date(s) indicated aside signatures:

	INVENTOR(S) (發明者フルネームサイン)	Date Signed (署名日)
1)	<u>Seiichiro KANNO</u> Seiichiro KANNO	<u>Feb. 19, 2001</u>
2)	<u>Ryoji Nishio</u> Ryoji NISHIO	<u>Feb. 19, 2001</u>
3)	<u>Tsutomu Tetsuka</u> Tsutomu TETSUKA	<u>Feb. 19, 2001</u>
4)	<u>Junichi Tanaka</u> Junichi TANAKA	<u>Feb. 20, 2001</u>
5)	<u>Hideyuki Yamamoto</u> Hideyuki YAMAMOTO	<u>Feb. 16, 2002</u>
6)	<u>Kazuyuki IKENAGA</u> Kazuyuki IKENAGA	<u>Feb. 19, 2001</u>
7)	<u>Saburou Kanai</u> Saburou KANAI	<u>Feb. 16, 2001</u>
8)	_____	_____
9)	_____	_____
10)	_____	_____